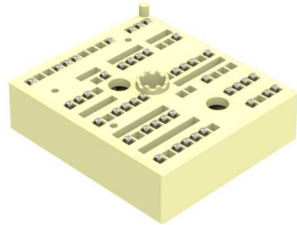
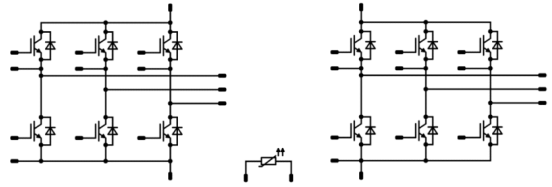




Vincotech

MiniSkiP PACK 2	1200 V / 25 A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #cccccc; margin: 0;">Features</p> <ul style="list-style-type: none"> Twin sixpack configuration for 4Q inverters Trench IGBT4 Technology Solderless spring contact mounting system </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #cccccc; margin: 0;">Target applications</p> <ul style="list-style-type: none"> Industrial Drives </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #cccccc; margin: 0;">Types</p> <ul style="list-style-type: none"> 80-M212WPB025SC-K388F </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #cccccc; margin: 0;">MiniSkiP 2 housing</p>  </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #cccccc; margin: 0;">Schematic</p>  </div>

Maximum Ratings

$T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ }^\circ\text{C}$	33	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	75	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ }^\circ\text{C}$	95	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j \leq 150\text{ }^\circ\text{C}$ $V_{GE} = 15\text{V}$	10 800	μs V
Maximum Junction Temperature	T_{jmax}		175	$^\circ\text{C}$



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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	27	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave $t_p = 10\text{ ms}$ $T_j = 150\text{ °C}$	100	A
Surge current capability	I^2t		50	A ² s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	69	W
Maximum Junction Temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...(T _{jmax} - 25)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	5500	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min. 12,7	mm
Clearance			min. 12,7	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	I_C [A]	T_j [°C]	Min	Typ	

Inverter Switch

Static

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$				0,00085	25		5,3	5,8	6,3	V
Collector-emitter saturation voltage	V_{CEsat}		15			25	25 125 150		1,6	1,96 2,22 2,28	2,2	V
Collector-emitter cut-off current	I_{CES}		0	1200			25				62,5	μA
Gate-emitter leakage current	I_{GES}		20	0			25				200	nA
Internal gate resistance	r_g									none		Ω
Input capacitance	C_{ies}	$f = 1$ MHz	0	25			25			1450		pF
Reverse transfer capacitance	C_{res}									50		

Thermal

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	Thermal grease thickness ≤ 50 μm $\lambda = 1$ W/mK								1,00		K/W

Dynamic

Parameter	Symbol	Conditions	V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 16$ Ω $R_{gon} = 16$ Ω	±15	600	25				25	71		ns
Rise time	t_r								150	72		
Turn-off delay time	$t_{d(off)}$								25	32		
Fall time	t_f								150	36		
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 1,5$ μC $Q_{tFWD} = 3,9$ μC							25	1,607		mWs
Turn-off energy (per pulse)	E_{off}								150	2,462		
									25	1,527		
									150	2,498		



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Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GS} [V]	V_{GE} [V] V_{DS} [V]	I_D [A] I_F [A]	I_C [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				25	25 150	1	2,47 2,49	2,8	V
Reverse leakage current	I_r			1200		25 150			60 3300	μA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	Thermal grease thickness $\leq 50 \mu\text{m}$ $\lambda = 1 \text{ W/mK}$						1,37		K/W
Dynamic										
Peak recovery current	I_{RRM}					25 150		12 17		A
Reverse recovery time	t_{rr}					25 150		278 580		ns
Recovered charge	Q_r	$di/dt = 690 \text{ A}/\mu\text{s}$ $di/dt = 578 \text{ A}/\mu\text{s}$	± 15	600	25	25 150		1,549 3,882		μC
Reverse recovered energy	E_{rec}					25 150		0,607 1,631		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 150		111 89		A/μs
Thermistor										
Rated resistance	R					25		1		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1670 \Omega$				100	-2		+2	%
R_{100}	R					100		1670		Ω
Power dissipation constant						25		0,76		mW/K
A-value	$A_{(25/50)}$					25		$7,635 \cdot 10^{-3}$		1/K
B-value	$B_{(25/100)}$					25		$1,731 \cdot 10^{-5}$		1/K ²
Vincotech PTC Reference									E	

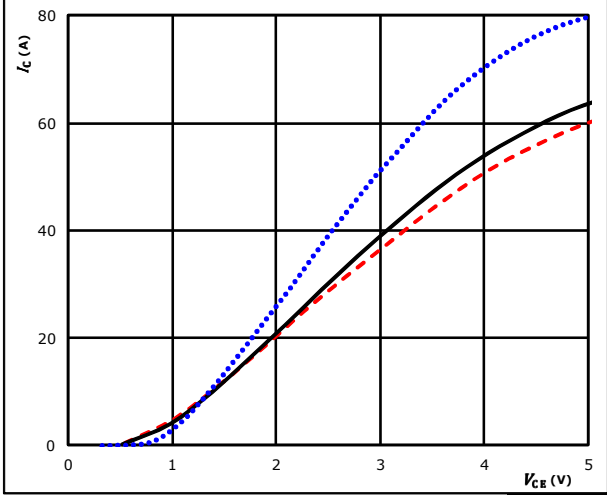


Inverter Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

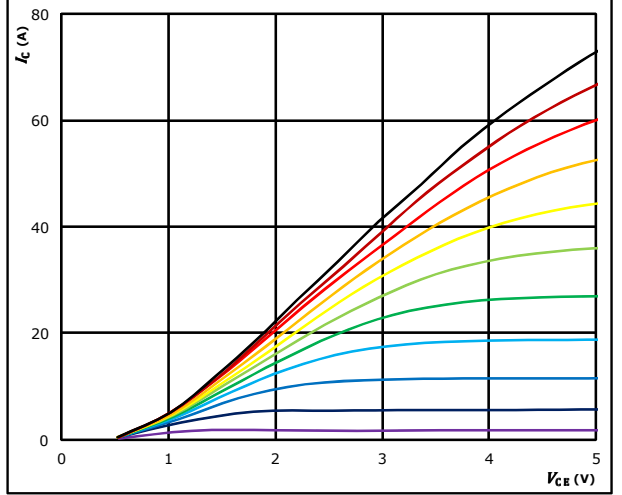


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25 \text{ }^\circ C$ (dotted blue)
 $125 \text{ }^\circ C$ (solid black)
 $150 \text{ }^\circ C$ (dashed red)

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

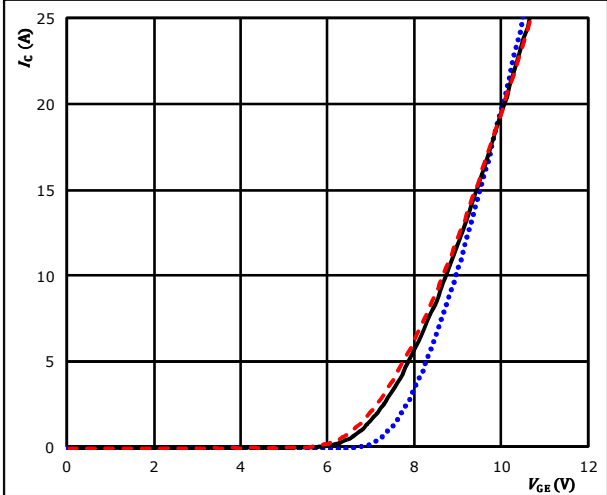


$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

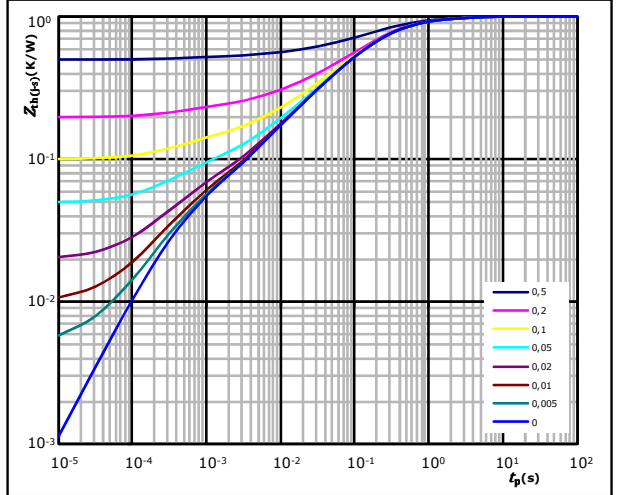


$t_p = 100 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25 \text{ }^\circ C$ (dotted blue)
 $125 \text{ }^\circ C$ (solid black)
 $150 \text{ }^\circ C$ (dashed red)

figure 4. IGBT

Transient Thermal Impedance as function of Pulse duration

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$
 $R_{th(j-s)} = 1,00 \text{ K/W}$

IGBT thermal model values

R (K/W)	τ (s)
4,33E-02	3,72E+00
2,16E-01	6,10E-01
4,68E-01	1,52E-01
1,79E-01	2,85E-02
5,59E-02	4,38E-03
3,78E-02	4,07E-04



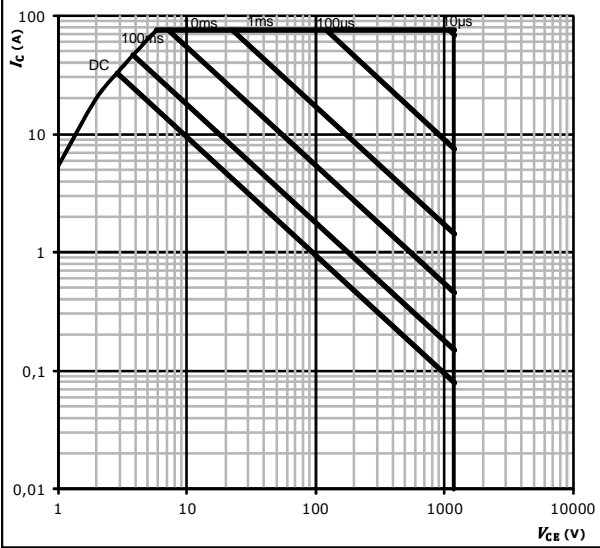
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Inverter Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



At

- $D =$ single pulse
- $T_s = 80$ °C
- $V_{GE} = \pm 15$ V
- $T_j = T_{jmax}$



Inverter Diode Characteristics

figure 1. FWD
Typical forward characteristics

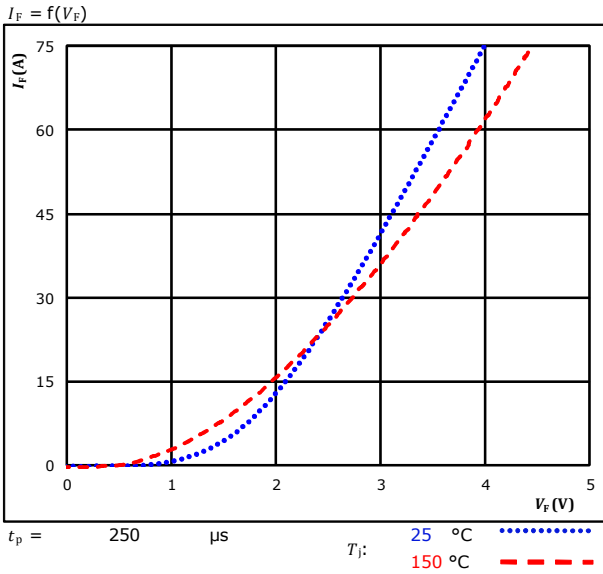
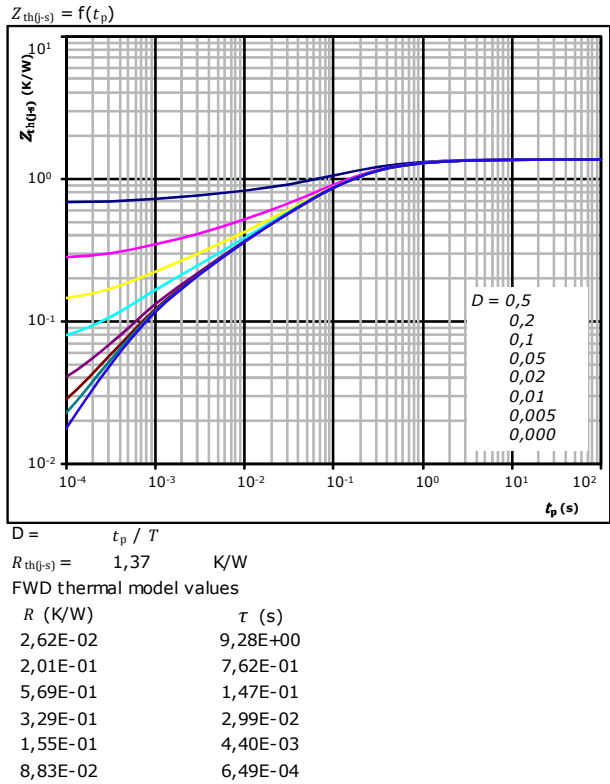


figure 2. FWD
Transient thermal impedance as a function of pulse width





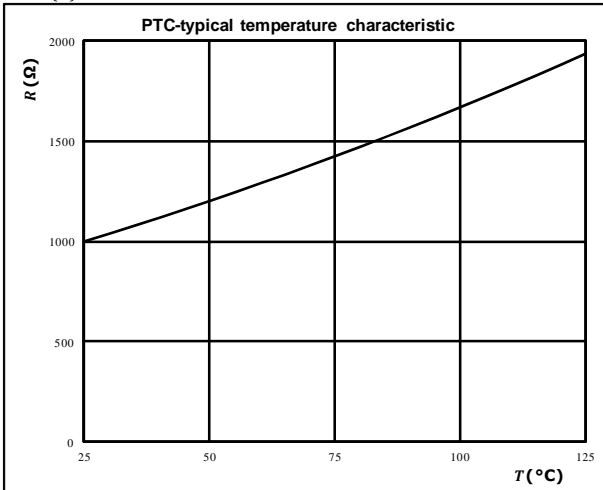
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Thermistor Characteristics

figure 1. Thermistor

Typical PTC characteristic
as a function of temperature

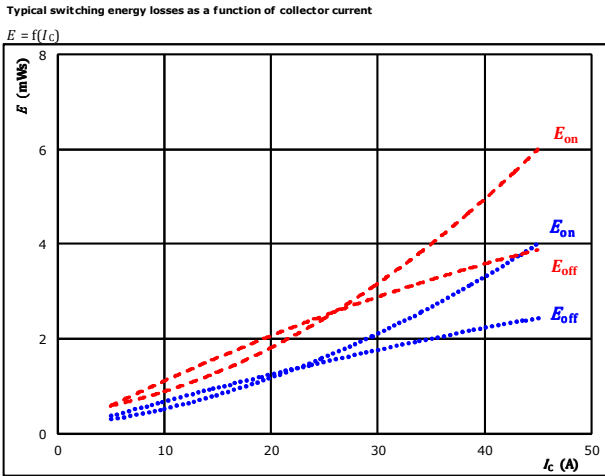
$$R = f(T)$$





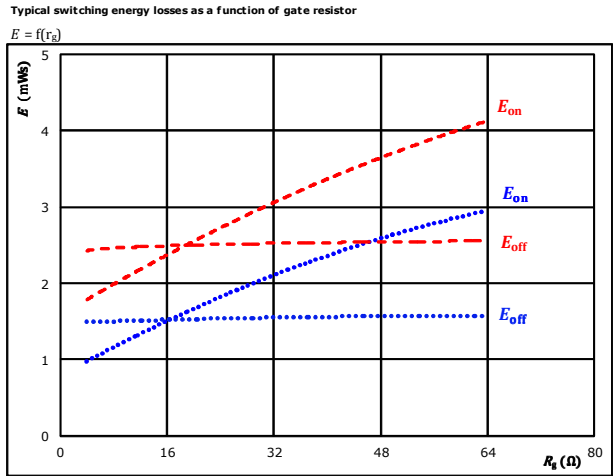
Inverter Switching Characteristics

Figure 1. IGBT
Typical switching energy losses as a function of collector current



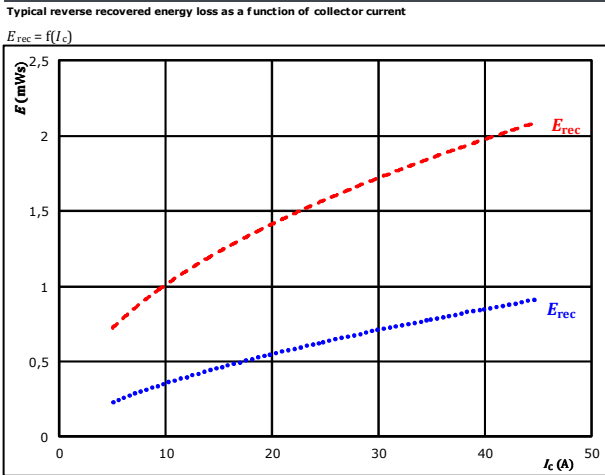
With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 16$ Ω
 $R_{goff} = 16$ Ω
 T_j : 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

Figure 2. IGBT
Typical switching energy losses as a function of gate resistor



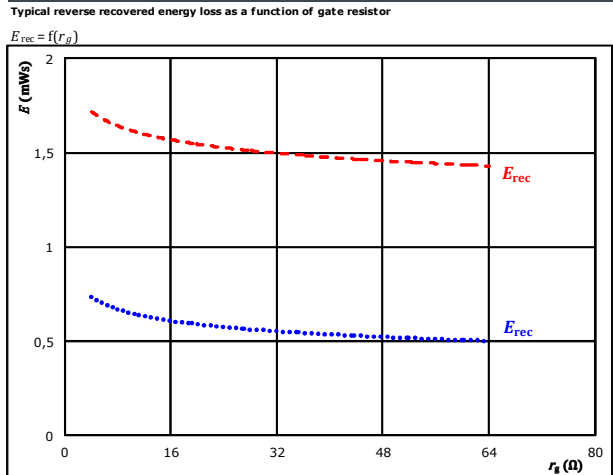
With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 25$ A
 T_j : 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

Figure 3. FWD
Typical reverse recovered energy loss as a function of collector current



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 16$ Ω
 T_j : 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

Figure 4. FWD
Typical reverse recovered energy loss as a function of gate resistor



With an inductive load at
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 25$ A
 T_j : 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

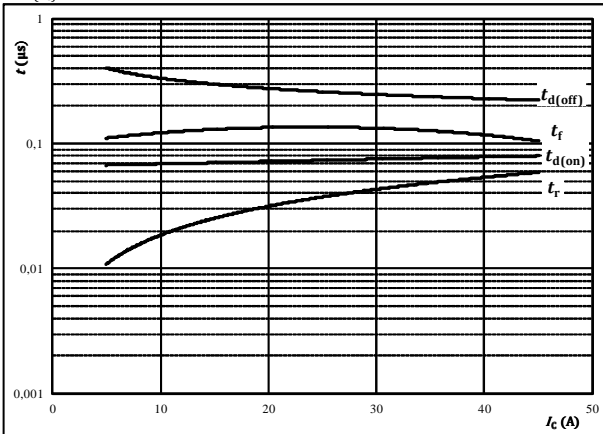


Inverter Switching Characteristics

Figure 5. IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



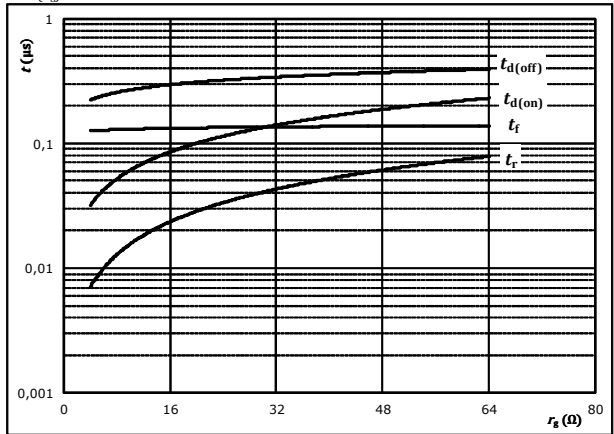
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	16	Ω
$R_{goff} =$	16	Ω

Figure 6. IGBT

Typical switching times as a function of gate resistor

$$t = f(r_g)$$



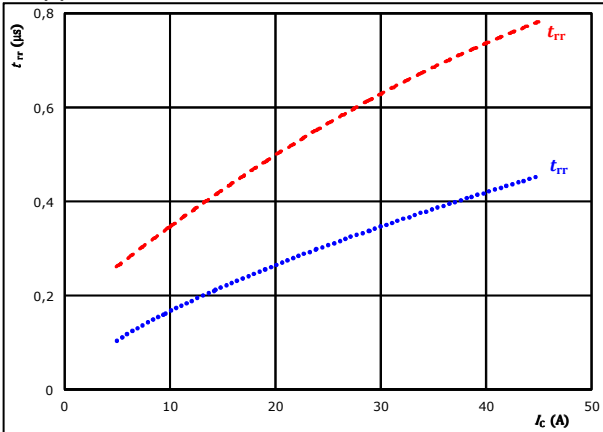
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$I_C =$	25	A

Figure 7. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$

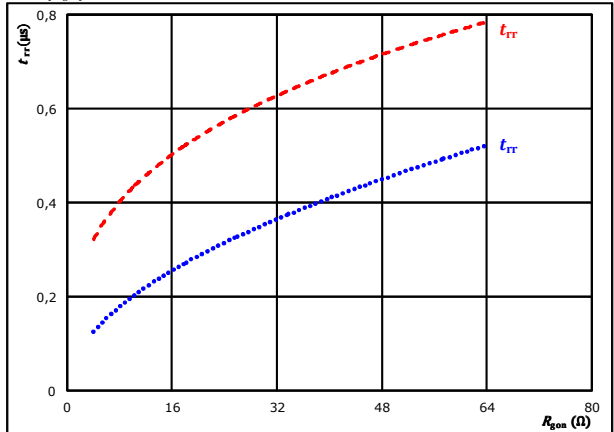


At	$V_{CE} =$	600	V	$T_j:$	25 °C
	$V_{GE} =$	±15	V		125 °C	————
	$R_{gon} =$	16	Ω		150 °C	-----

Figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At	$V_{CE} =$	600	V	$T_j:$	25 °C
	$V_{GE} =$	±15	V		125 °C	————
	$I_C =$	25	A		150 °C	-----

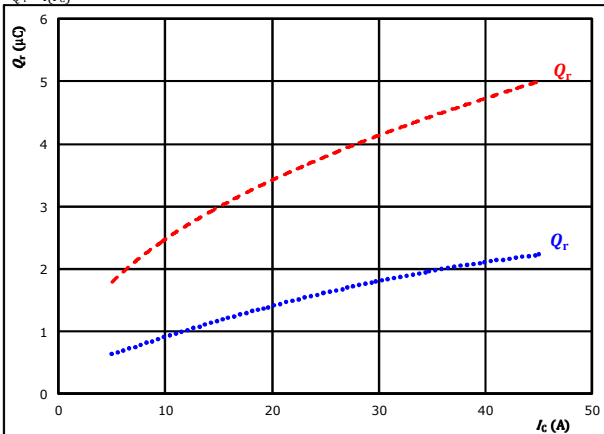


Inverter Switching Characteristics

Figure 9. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$

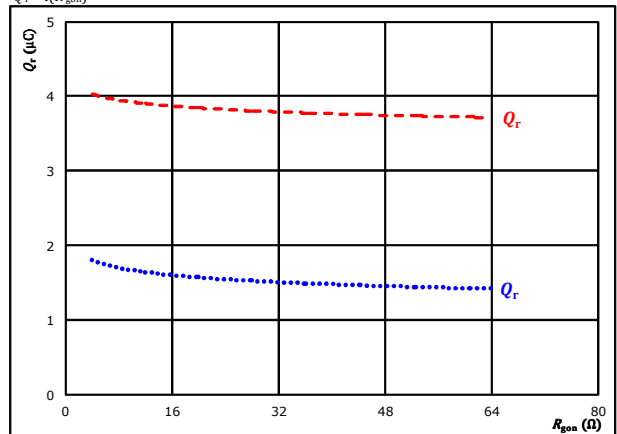


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gpn} = 16$ Ω
 T_j : 25 °C (dotted blue line)
 125 °C (solid black line)
 150 °C (dashed red line)

Figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gpn})$$

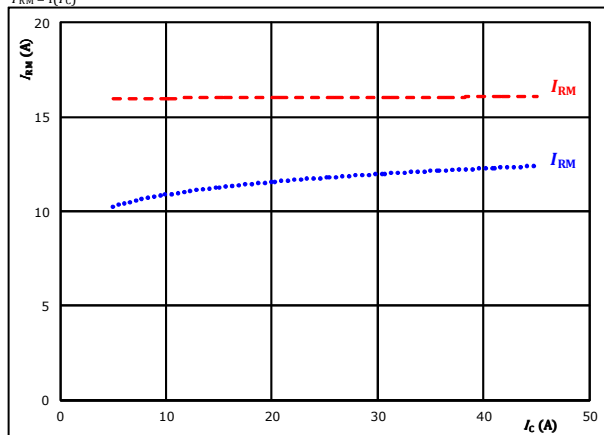


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 25$ A
 T_j : 25 °C (dotted blue line)
 125 °C (solid black line)
 150 °C (dashed red line)

Figure 11. FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$

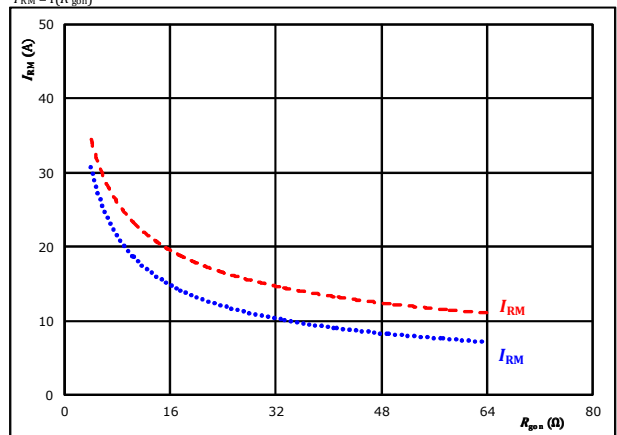


At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gpn} = 16$ Ω
 T_j : 25 °C (dotted blue line)
 125 °C (solid black line)
 150 °C (dashed red line)

Figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gpn})$$



At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 25$ A
 T_j : 25 °C (dotted blue line)
 125 °C (solid black line)
 150 °C (dashed red line)

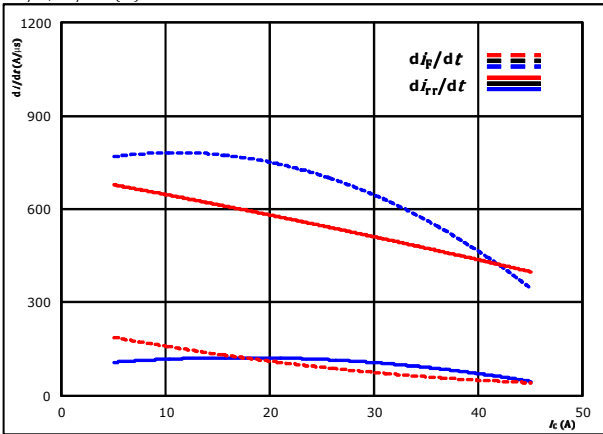


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Inverter Switching Characteristics

Figure 13. FWD

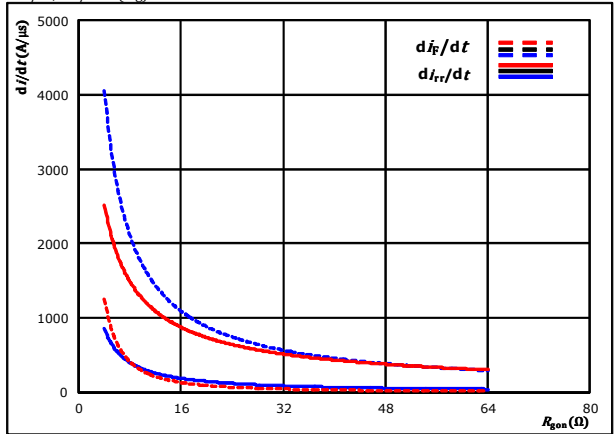
Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_c)$



At $V_{CE} = 600$ V $T_j = 25$ °C $\dots\dots\dots$
 $V_{GE} = \pm 15$ V 125 °C ---
 $R_{gon} = 16$ Ω 150 °C ---

Figure 14. FWD

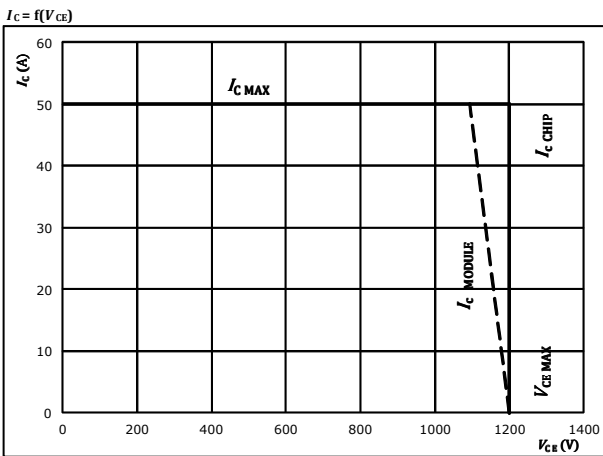
Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_g)$



At $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_c = 25$ A

Figure 15. IGBT

Reverse bias safe operating area



At $T_j = 175$ °C
 $R_{gon} = 16$ Ω
 $R_{goff} = 16$ Ω



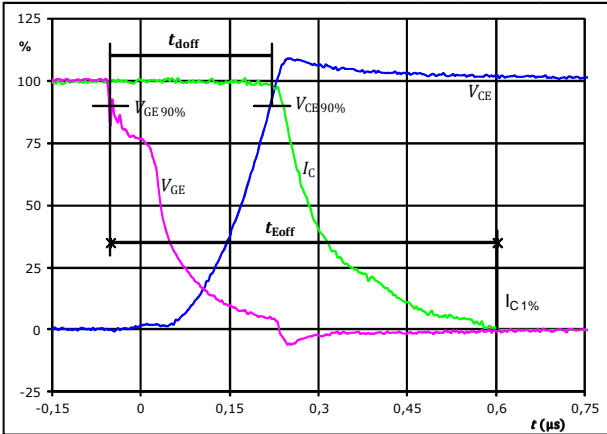
Inverter Switching Definitions

General conditions

T_j	=	150 °C
R_{gon}	=	16 Ω
R_{goff}	=	16 Ω

Figure 1. IGBT

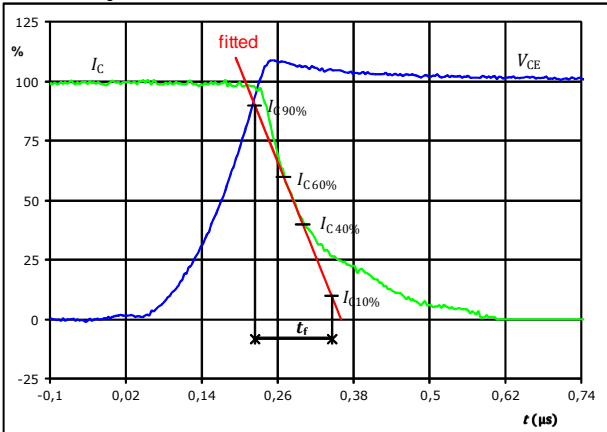
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%) =$	-15	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	25	A
$t_{doff} =$	0,270	μs
$t_{Eoff} =$	0,653	μs

Figure 3. IGBT

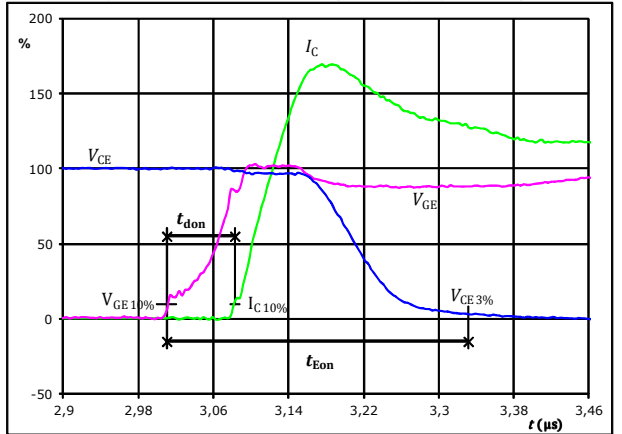
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%) =$	600	V
$I_C(100\%) =$	25	A
$t_f =$	0,135	μs

Figure 2. IGBT

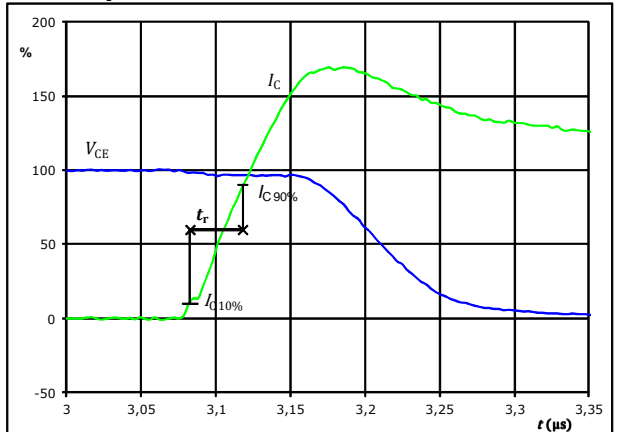
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%) =$	-15	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	25	A
$t_{don} =$	0,072	μs
$t_{Eon} =$	0,321	μs

Figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r



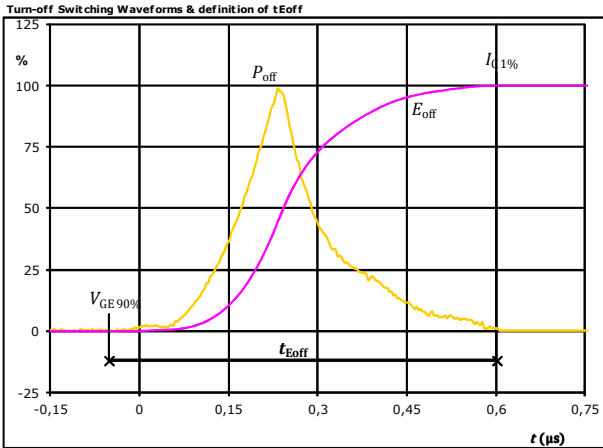
$V_C(100\%) =$	600	V
$I_C(100\%) =$	25	A
$t_r =$	0,036	μs



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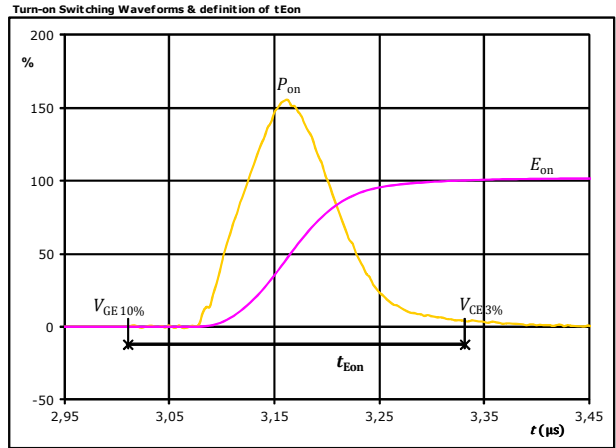
Inverter Switching Characteristics

Figure 5. IGBT



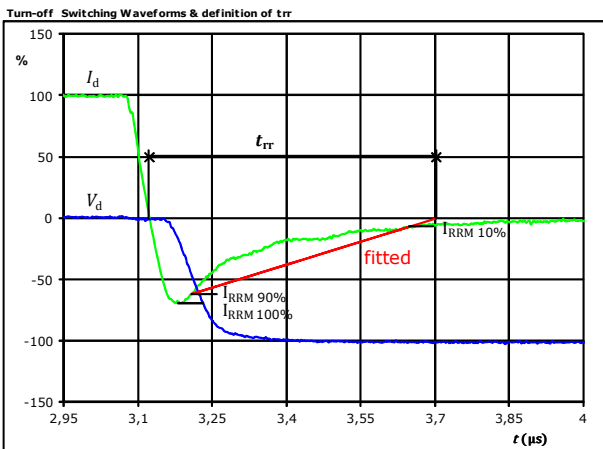
$P_{off}(100\%) = 15,03$ kW
 $E_{off}(100\%) = 2,50$ mJ
 $t_{Eoff} = 0,65$ µs

Figure 6. IGBT



$P_{on}(100\%) = 15,03$ kW
 $E_{on}(100\%) = 2,46$ mJ
 $t_{Eon} = 0,321$ µs

Figure 7. FWD



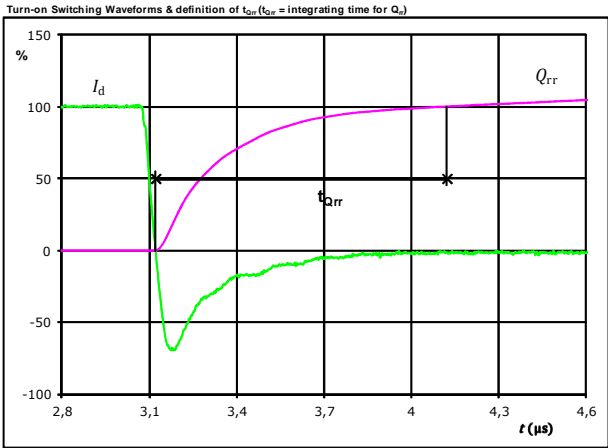
$V_d(100\%) = 600$ V
 $I_d(100\%) = 25$ A
 $I_{RRM}(100\%) = -17$ A
 $t_{rr} = 0,580$ µs



Vincotech

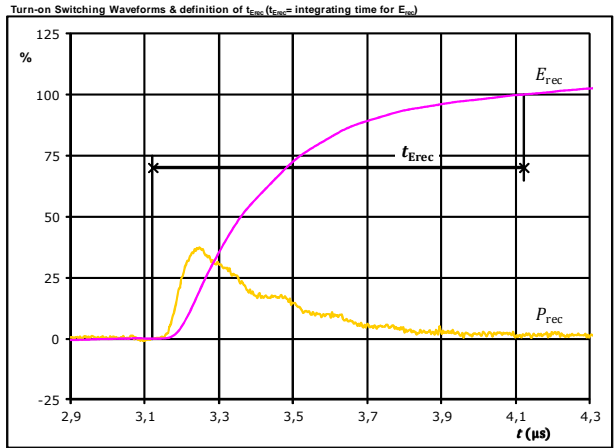
Inverter Switching Characteristics

Figure 8. FWD



I_d (100%) = 25 A
 Q_{rr} (100%) = 3,88 μC
 t_{Qrr} = 1,00 μs

Figure 9. FWD



P_{rec} (100%) = 15,03 kW
 E_{rec} (100%) = 1,63 mJ
 t_{Erec} = 1,00 μs



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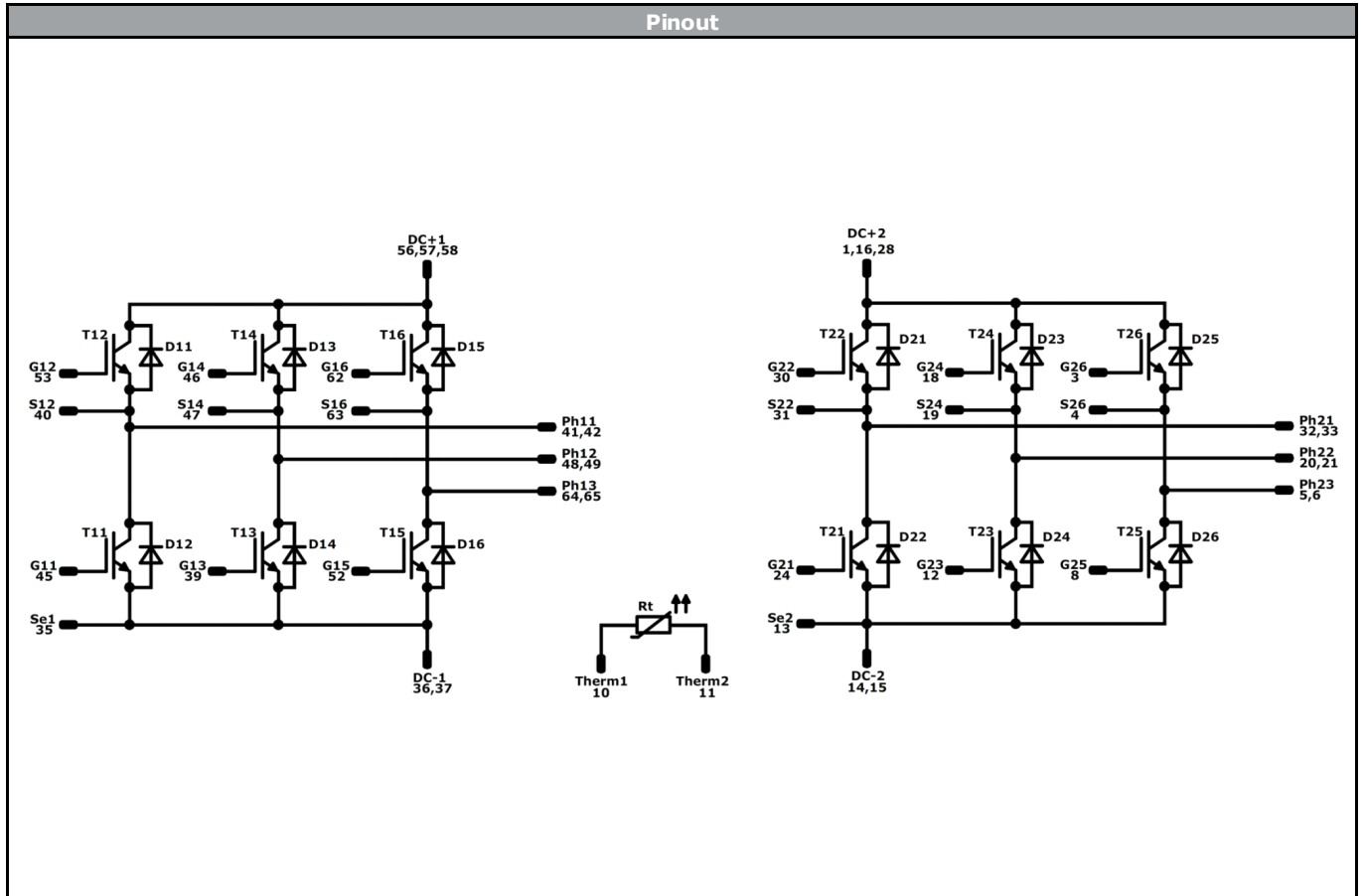
Ordering Code & Marking								
Version			Ordering Code					
with std lid (black V23990-K22-T-2-PM) with thermal paste			80-M212WPB025SC-K388F-1A/					
with thin lid (white V23990-K23-T-3-PM) with thermal paste			80-M212WPB025SC-K388F-1B/					
NN-NNNNNNNNNNNNNN TTTTUVVWWYY UL VIN LLLLL SSSS			Name		Date code	UL & VIN	Lot	Serial
			NN-NNNNNNNNNNNNNN-TTTTUVV		WWYY	UL VIN	LLLLL	SSSS
			Type&Ver	Lot number	Serial	Date code		
Datamatrix			TTTTTUVV	LLLLL	SSSS	WWYY		

Outline							
PCB pad table				PCB pad table			
Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,8	DC+2	52	-12,22	21,8	G15
2	Not assembled			53	-24,38	-21,8	G12
3	24,38	-15,4	G26	54	Not assembled		
4	24,38	-12,2	S26	55	Not assembled		
5	24,38	-9	Ph23	56	-24,38	-12,2	DC+1
6	24,38	-5,8	Ph23	57	-24,38	-9	DC+1
7	Not assembled			58	-24,38	-5,8	DC+1
8	24,38	12,2	G25	59	Not assembled		
9	Not assembled			60	Not assembled		
10	24,38	18,6	Therm1	61	Not assembled		
11	24,38	21,8	Therm2	62	-24,38	7,1	G16
12	16,58	12,2	G23	63	-24,38	15,4	S16
13	16,58	15,4	Se2	64	-24,38	18,6	Ph13
14	16,58	18,6	DC-2	65	-24,38	21,8	Ph13
15	16,58	21,8	DC-2				
16	13,42	-21,8	DC+2				
17	Not assembled						
18	13,42	-15,4	G24				
19	13,42	-12,2	S24				
20	13,42	-9	Ph22				
21	13,42	-5,8	Ph22				
22	Not assembled						
23	Not assembled						
24	8,38	12,2	G21				
25	Not assembled						
26	Not assembled						
27	Not assembled						
28	2,46	-21,8	DC+2				
29	Not assembled						
30	2,46	-15,4	G22				
31	2,46	-12,2	S22				
32	2,46	-9	Ph21				
33	2,46	-5,8	Ph21				
34	Not assembled						
35	0,03	9	Se1				
36	0,03	12,2	DC-1				
37	0,03	15,4	DC-1				
38	Not assembled						
39	0,03	21,8	G13				
40	-8,5	-21,8	S12				
41	-8,5	-18,6	Ph11				
42	-8,5	-15,4	Ph11				
43	Not assembled						
44	Not assembled						
45	-12,22	-5,8	G11				
46	-12,22	0,7	G14				
47	-12,22	3,9	S14				
48	-12,22	7,1	Ph12				
49	-12,22	10,3	Ph12				
50	Not assembled						
51	Not assembled						

Pad positions refers to center point. For more informations on pad design please see package data



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Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12, T13 T14, T15, T16 T21, T22, T23 T24, T25, T26	IGBT	1200 V	25 A	Inverter Switch	
D11, D12, D13 D14, D15, D16 D21, D22, D23 D24, D25, D26	FWD	1200 V	25 A	Inverter Diode	
Rt	Thermistor			Thermistor	




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Packaging instruction			
Standard packaging quantity (SPQ) 72	>SPQ	Standard	<SPQ Sample

Handling instruction
Handling instructions for MiniSkiiP® 2 packages see vincotech.com website.

Package data
Package data for MiniSkiiP® 2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
80-M212WPB025SC-K388F-D2-14	04 Sep. 2017	New ordering option added	16

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.